PAUL SCHERRER INSTITUT

PICO

Oxford Instruments Argon Ion Miller “Ionfab 300plus”

Responsible

Anja Weber

System description

2 Sources 15cm for max. 4-inch wafers with broad beam

For Ion Beam Etching and Ion Beam Deposition (currently targets available Ta, Cu)

Connected gases: Argon, Nitrogen and Oxygen

Argon for milling

Sample Tilt up to 60° for ion beam milling,

Sample rotation up to 20 rpm

Materials allowed to be decided by LNQ Labmanagement